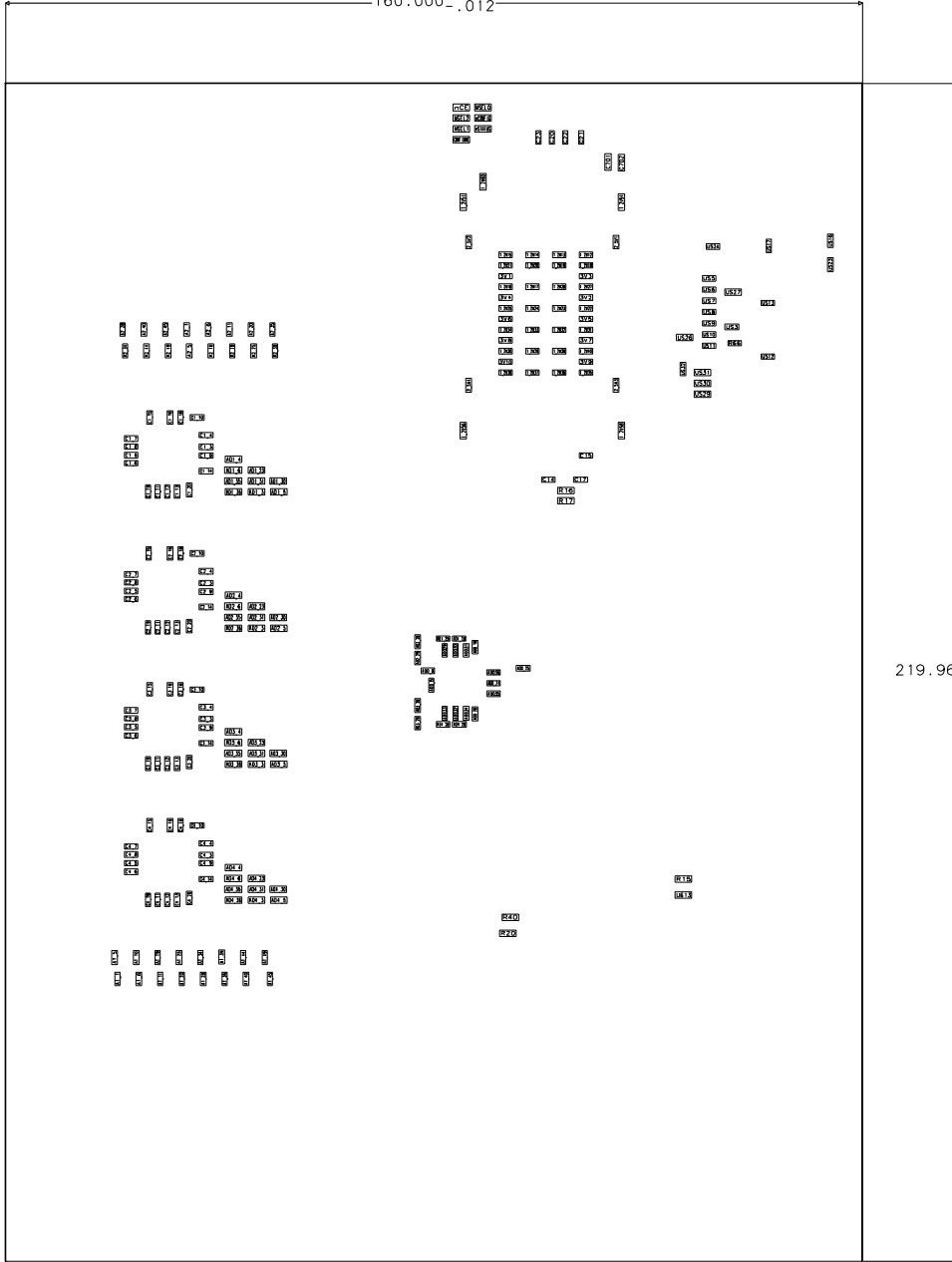


160.000⁺.000
 160.000⁻.012



219.964⁺.000
 219.964⁻.012

Notes:

1. Some parts will not be installed, see BOM file.
2. Dimensions in mm.
3. No Centroid data provided. Assembly house shall generate it from Gerber Files if needed.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS FRACTIONS DECIMALS ANGLES		CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP	
BY THE SCALE DRAWING		APPROVALS	DATE	PSEC2 Flip Chip ADC Module	
DRAWN		BY	DATE	Assembly drawing - Bottom	
CHECKED		BY	DATE	SIZE	SEC. NO.
DESIGNED		BY	DATE	SCALE	SHEET
TITLE		REV. NO.		REV. NO.	